



# Nano Diamond Thermal Compound

Model No. / 型號

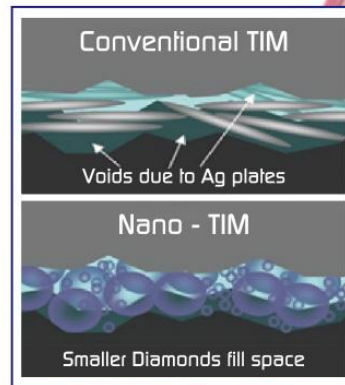
HTC-03



The Evercool new released thermal compound – HTC-03 is composed of Nano Diamond particles. The thermal conductive is up to 12 (W/mk). It is especially suitable for CPU / GPU high heating power module. Non-electrical conductive and viscosity make it easy to spread or remove. The non-curing and non-electrical conductive traits help avoid any short circuiting and provides protection and performance for long-term use.

## ● Features / 特色

- With its Nano Diamond nature thermal conductor, HTC-03 has higher thermal conduction efficiency.
- High stability and not easily solidify.
- Not electrically conductive.
- Cleanser can effectively remove thermal compound from heatsink.
- Spreader makes applying thermal compound easier.
- 奈米鑽石結構導熱膏，可以填補更細小的空隙，提高導熱膏性能
- 長時間運作不會發生硬化現象·穩定性高
- 不導電材質，避免電子元件短路問題
- 附上導熱膏清潔布，清潔導熱膏更快速方便



## ● Specification / 規格

- Contents/內容物：  
Thermal compound/導熱膏\*1、Spreader/刮刀\*1、Grease Cleanser/導熱膏擦拭布\*1
- Color/顏色：Gray/灰色
- Thermal Conductivity/熱傳導係數：12 W/m-k
- Specific Gravity/比重：2.8 g/cm<sup>3</sup>
- Main Components/主要成分：  
Nano diamond, silicon/奈米鑽石結構及矽化合物
- Working Temperature/操作溫度：-50°C to 250°
- Weight/內容物重量：5g

## 20 nm Diamond Particle

